

CLAIMS

1. An electronic device unit ~~A heat sink~~ comprising:

a heat sink including:

_____a base plate;

5 _____a protrusion protruding from the base plate in a first direction intersecting the base plate, the protrusion being thermally connectable to a first heating element mounted on a first substrate;

_____a plurality of first fins protruding from the base plate in an opposite direction to the first direction, the plurality of first fins being aligned in a second
10 direction intersecting the first direction;

_____a first boss protruding from the base plate more than the plurality of first fins in the opposite direction to the first direction, the first boss allowing a fastener to be attached to the first boss, the fastener serving to couple an outer wall of a housing and the base plate; and

15 _____a second boss protruding from the base plate in the first direction, the second boss allowing a fastener to be attached to the second boss, the fastener serving to couple the first substrate and the base plate;

a first substrate on which a first heating element is mounted in a state where the first heating element is thermally connected to the protrusion of the heat sink;

20 an attachment base being placed on a side opposite to the heat sink in the first direction from the first substrate;

a second substrate being placed in the first direction from the attachment base;
and

a storage holder being placed in the first direction from the second substrate to hold an auxiliary storage device, wherein

the electronic device unit is configured to be attachable to a housing in a state where the heat sink, the first substrate, the attachment base, the second substrate, and the storage holder are integrated with one another, and

the attachment base includes

a middle wall being placed between the first substrate and the second substrate,

a first stud protruding from the middle wall in the opposite direction to the first direction, the first stud allowing a fastener to be attached to the first stud, the fastener serving to couple the first substrate and the attachment base, and

a second stud protruding from the middle wall in the first direction, the second stud allowing a fastener to be attached to the second stud, the fastener serving to couple the second substrate and the attachment base.

15

2. The electronic device unit ~~heat sink~~ according to claim 1, wherein

the protrusion includes a concavity being concave in the first direction from a first surface on a side opposite to the first heating element, and

part of the plurality of first fins protrudes from a bottom portion of the concavity in the opposite direction to the first direction.

20

3. The electronic device unit ~~heat sink~~ according to claim 1 or 2, further comprising a plurality of second fins protruding from the base plate in the first direction, the plurality of second fins being aligned in the second direction.

5 4. ~~An electronic device unit comprising:~~
~~the heat sink according to any one of claims 1 to 3;~~
~~a first substrate on which a first heating element is mounted in a state where the~~
~~first heating element is thermally connected to the protrusion of the heat sink;~~
~~an attachment base being placed on a side opposite to the heat sink in the first~~
10 ~~direction from the first substrate;~~
~~a second substrate being placed in the first direction from the attachment base;~~
~~and~~
~~a storage holder being placed in the first direction from the second substrate to~~
~~hold an auxiliary storage device;~~
15 ~~wherein the electronic device unit is configured to be attachable to a housing in~~
~~a state where the heat sink, the first substrate, the attachment base, the second substrate,~~
~~and the storage holder are integrated with one another.~~

5. ~~The electronic device unit according to claim 4, wherein the attachment base~~
20 ~~includes~~
~~a middle wall being placed between the first substrate and the second substrate;~~

~~—— a first stud protruding from the middle wall in the opposite direction to the first direction, the first stud allowing a fastener to be attached to the first stud, the fastener serving to couple the first substrate and the attachment base, and~~

~~—— a second stud protruding from the middle wall in the first direction, the second stud allowing a fastener to be attached to the second stud, the fastener serving to couple the second substrate and the attachment base.~~

64. The electronic device unit according to claim ~~14~~ or 5, further comprising a second heating element being mounted on the first substrate or the second substrate, the second heating element being provided in a state where the second heating element is thermally connected to the attachment base through a heat conducting member,

wherein the heat conducting member includes

a grease being applied on the attachment base, and

a sheet being interposed between the grease and the second heating element.

75. The electronic device unit according to claim 64, wherein the storage holder includes a heat insulating wall covering at least a second surface of the auxiliary storage device, the second surface being located in the opposite direction to the first direction.